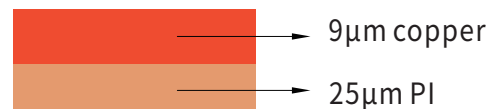


GFI-S900G

特色優勢 Features

- 優越的尺寸安定性及高剝離力，同時採用無膠結構，不溢膠、不殘膠適合於高溫或低溫環境用，環測後不分層不起泡。
- 採用真空濺鍍工藝，無牙根、表面極平坦化，銅粒子晶格微小及穩定，易於蝕刻控，可輕易製作Pitch < 30um之細線路。
- 本產品可依需求製作0.1um~9um任意厚度，並具備優越的銅厚均勻性，可搭配m-SAP製程，實現高深寬比的細路品質。
- This product has superior dimensional stability and high peeling force, and adopts a glue-free structure, no glue overflow, no glue residue, suitable for high or low temperature environments, no delamination and no foaming after environmental testing.
- This product adopts vacuum sputtering process, no tooth root, extremely flat surface, copper particle lattice is small and stable, easy to etch control, and can easily make pitch < 30um fine lines.
- This product can be made of any thickness of 0.1um~9um according to requirements, and has superior copper thickness uniformity, and can be used with m-SAP process to achieve high aspect ratio of fine road quality.

產品結構Structure



技術參數 Technical Data

項目 ITEM		單位UNIT	規格SPEC.	檢測標準TEST STANDARD
基材厚度 Thickness		μm	25 ± 2.5	Micro Meter
鍍層厚度 Determination of Metallic Foils		μm	9± 1.5	Film thickness tester
產品厚度 Total Thickness		μm	34±4	Micro Meter
拉力測試 ^a Peel Strength ^a		kgf/cm	> 0.6	IPC-TM-650 2.4.9
抗張強度 Tensile Strength		MPa	> 260	ASTM D638
尺寸安定性 Dimensional Stability	M.D.	%	-0.2~0.2	IPC-TM-650 2.2.4
	T.D.			
PI阻抗 Volume Resistivity		Ω-cm	≥1x10 ¹⁴	ohmmeter
UL阻燃等級 Flammability Rating		/	V-0	UL94
寬幅 Width		mm	250 +3/-0	

^a 試樣厚度增厚到18um，150度烤60分鐘後測試。
Thickness of specimen is 18μm, Test after roasted at 150°C for 60 minutes

環保測試 Environmental

符合RoHS 與歐盟無鹵標準
RoHS compliant and EU halogen-free

LYE reserve the right to replacement of the main substrate and the protective film and to inform the customer before the replacement.